

## 1. Features

This Power MOSFET is produced using KIA advanced planar stripe TRENCH technology. This advanced technology has been especially tailored to minimize conduction loss, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

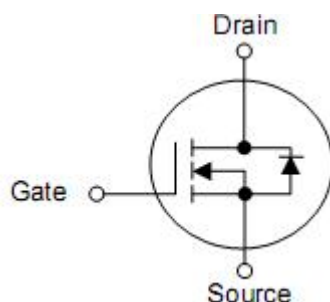
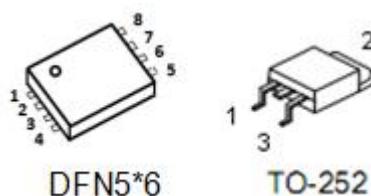
## 2. Features

- n  $R_{DS(ON)}=83m\Omega(\text{typ.})@V_{GS}=10V$
- n Very Low On-resistance  $R_{DS(ON)}$
- n Low  $C_{rss}$
- n Fast switching
- n 100% avalanche tested
- n Improved  $dv/dt$  capability

## 3. Applications

- n PWM Application
- n Power Management
- n Load switch

## 4. Symbol



Pin		Function
DFN5*6	TO-252	
1,2,3	3	Source
4	1	Gate
5,6,7,8	2	Drain

## 5. Ordering Information

Part Number	Package	Brand
KNY6610A	DFN5*6	KIA
KND6610A	TO-252	KIA

## 6. Absolute maximum ratings

$T_C=25^\circ\text{C}$  unless otherwise noted

Parameter	Symbol	Rating	Units	
Drain-source voltage	$V_{DSS}$	100	V	
Continuous drain current	$T_C=25^\circ\text{C}$	$I_D$	15	A
	$T_C=100^\circ\text{C}$	$I_D$	10	A
Pulsed drain current -Pulsed <sup>1)</sup>	$I_{DM}$	60	A	
Gate-source voltage	$V_{GS}$	$\pm 20$	V	
Single pulse avalanche energy <sup>2)</sup>	$E_{AS}$	3.5	mJ	
Power dissipation ( $T_C=25^\circ\text{C}$ )	$P_D$	55	W	
Operating junction and storage temperature range	$T_J, T_{STG}$	-55 to 150	$^\circ\text{C}$	
Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	TL	300	$^\circ\text{C}$	

<sup>1)</sup>Drain current limited by maximum junction temperature.

## 7. Thermal characteristics

Parameter	Symbol	Rating	Unit
Thermal resistance junction-case	$R_{\theta JC}$	2.73	$^\circ\text{C/W}$

## 8. Electrical characteristics

( $T_C=25^{\circ}\text{C}$ , unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Drain-source breakdown voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	100	-	-	V
Drain-source leakage current	$I_{DSS}$	$V_{DS}=100V, V_{GS}=0V$	-	-	1	$\mu A$
Gate-source forward leakage	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 1$	$\mu A$
Gate threshold voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0	1.7	2.5	V
Drain-source on-resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=10A$	-	83	110	$m\Omega$
		$V_{GS}=4.5V, I_D=8A$	-	90	130	$m\Omega$
Input capacitance	$C_{iss}$	$V_{DS}=25V, V_{GS}=0V$ $f=1MHz$	-	1073	-	$pF$
Output capacitance	$C_{oss}$		-	57	-	$pF$
Reverse transfer capacitance	$C_{rss}$		-	31	-	$pF$
Turn-on delay time	$t_{d(on)}$	$V_{GS}=10V, V_{DS}=30V,$ $R_G=1.8\Omega, I_D=10A^{3)}$		12.6		ns
Rise time	$t_r$			6		ns
Turn-off delay time	$t_{d(off)}$			32.5		ns
Fall time	$t_f$			4.3		ns
Total gate charge(10V)	$Q_g$	$V_{DS}=30V, I_D=15A$ $V_{GS}=10V^{3)}$	-	19.2	-	nC
Gate-source charge	$Q_{gs}$		-	3.4	-	nC
Gate-drain charge	$Q_{gd}$		-	6.1	-	nC
Maximum Continuous Drain-Source Diode Forward Current	$I_S$	—	-	-	15	A
Maximum Pulsed Drain-Source Diode Forward Current	$I_{SM}$	—	-	-	60	A
Diode forward voltage	$V_{SD}$	$I_{SD}=15A, V_{GS}=0V,$ $T_J=25^{\circ}\text{C}$	-	-	1.2	V

Note:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
2. EAS condition :  $T_J=25^{\circ}\text{C}, V_{DD}=30V, V_G=10V, L=0.5mH, R_g=25\Omega, I_{AS}=3.75A$
3. Pulse Test: Pulse Width $\leq 300\mu s$ , Duty Cycle $\leq 0.5\%$

9. Typical operating characteristics

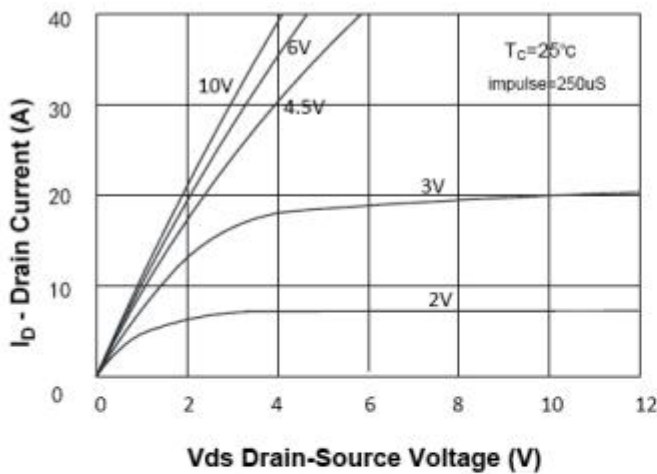


Figure 1. On-Region Characteristics

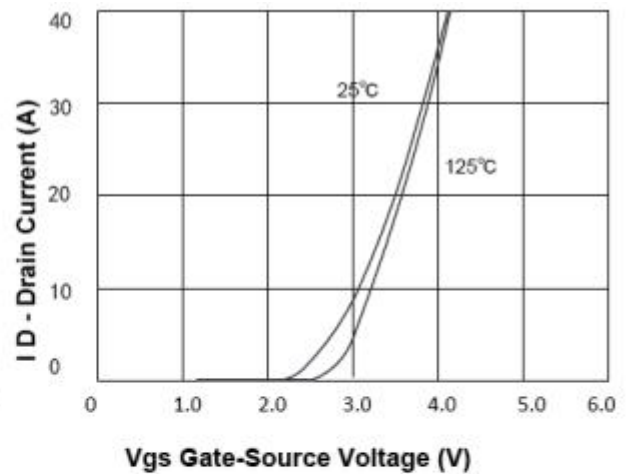


Figure 2. Transfer Characteristics

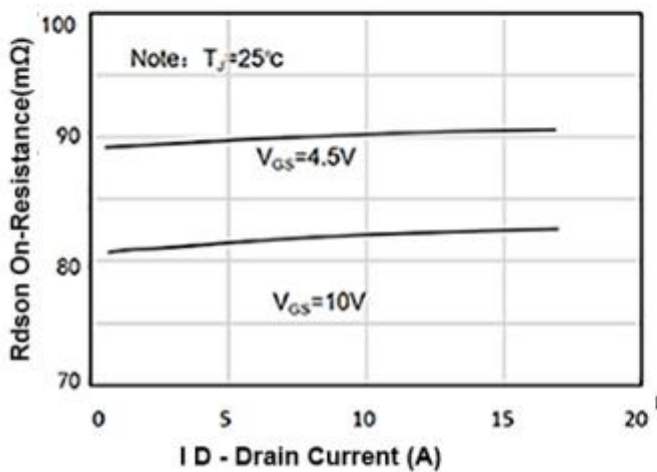


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

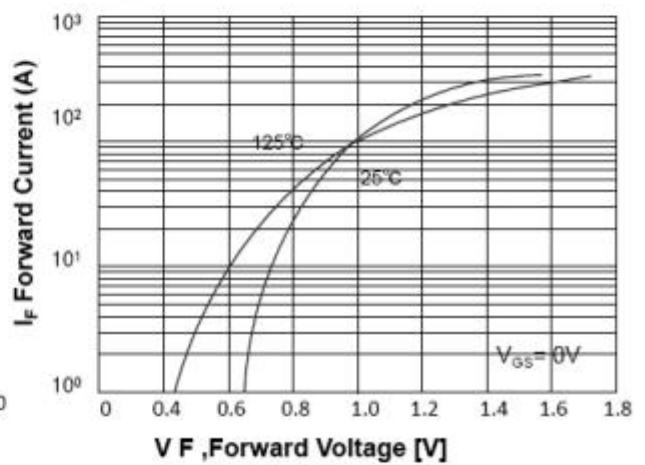


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

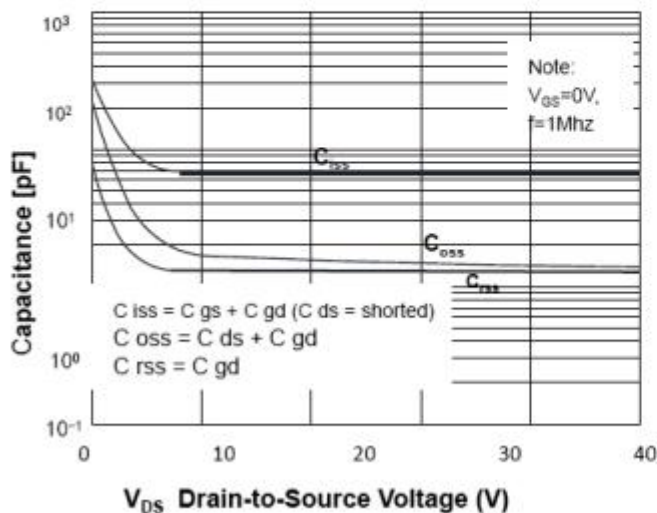


Figure 5. Capacitance Characteristics

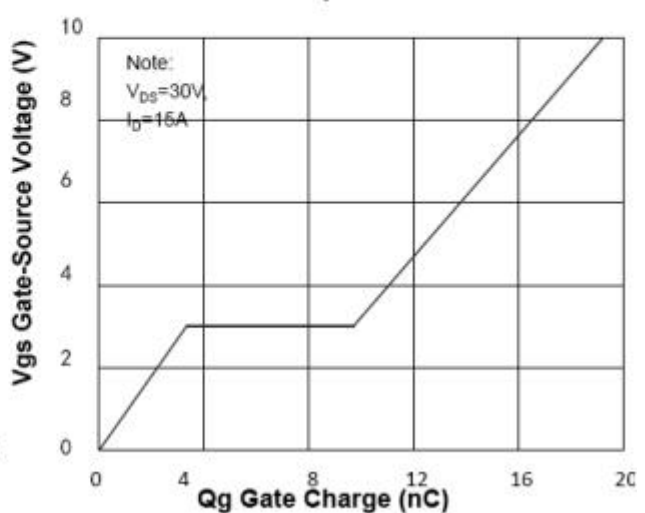
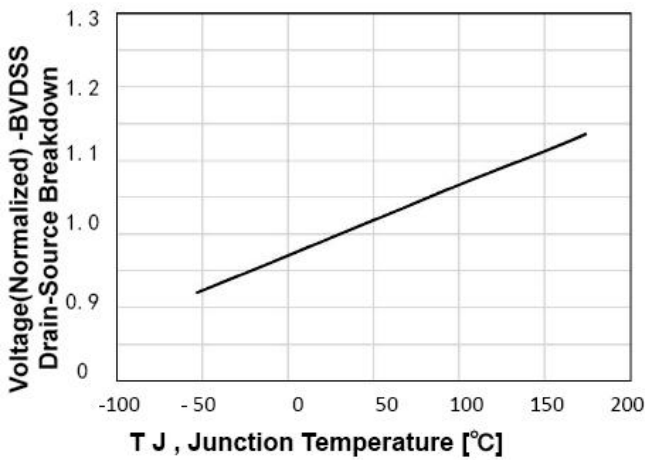
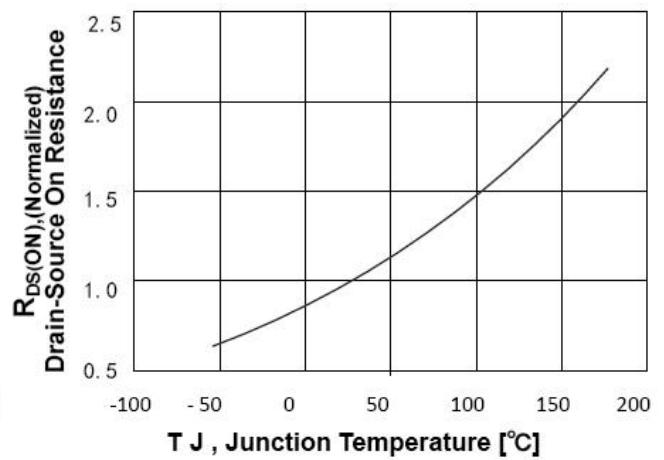


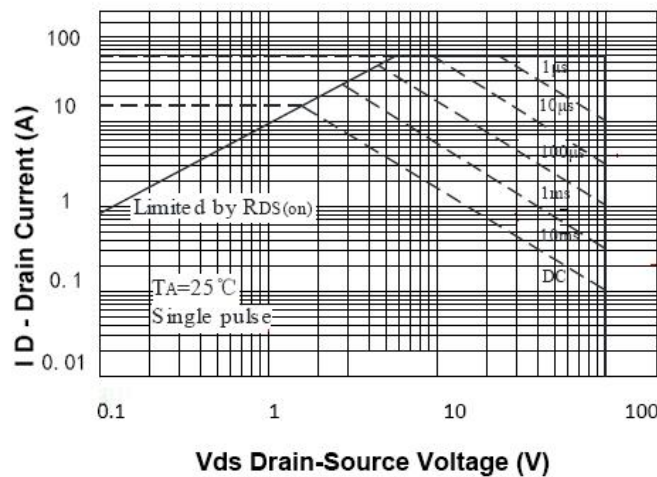
Figure 6. Gate Charge Characteristics



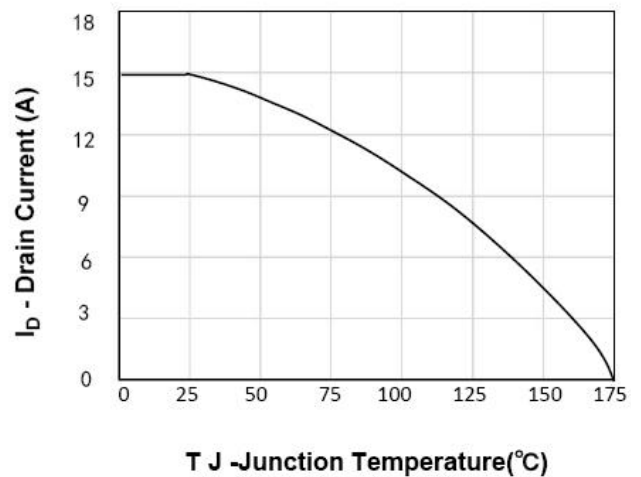
**Figure 7. Breakdown Voltage Variation vs Temperature**



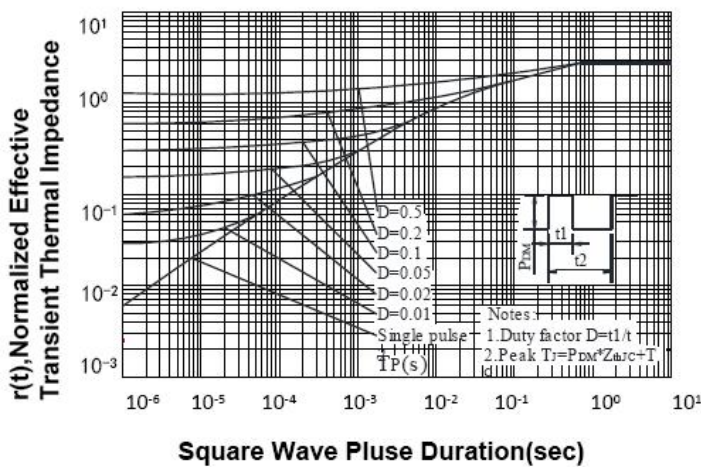
**Figure 8. On-Resistance Variation vs Temperature**



**Figure 9. Maximum Safe Operating Area**



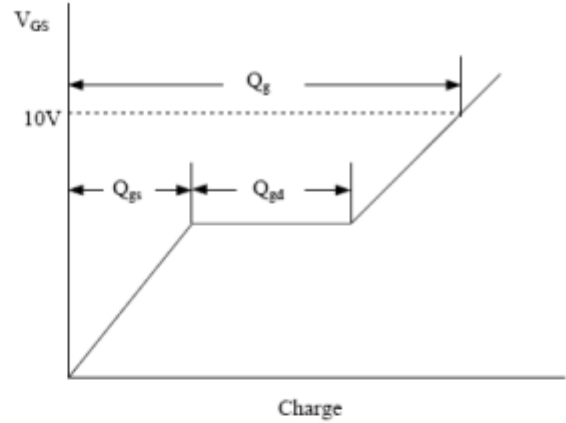
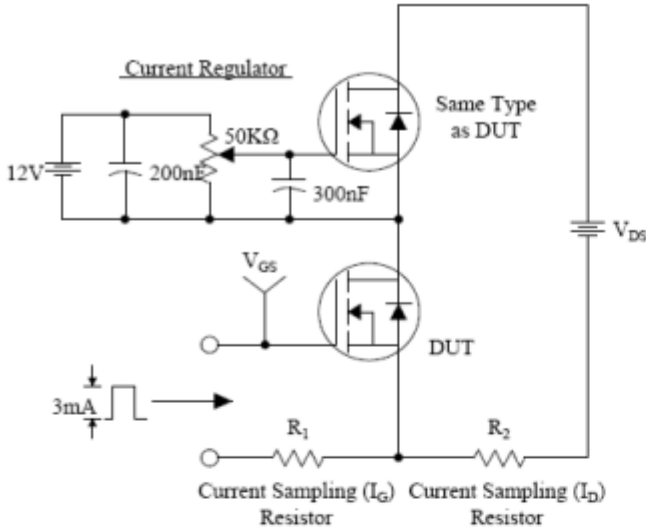
**Figure 10. Maximum PContinuous Drain Current vs Case Temperature**



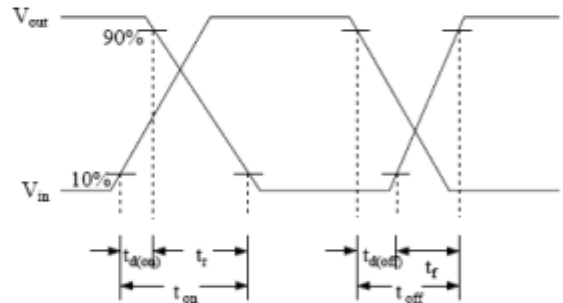
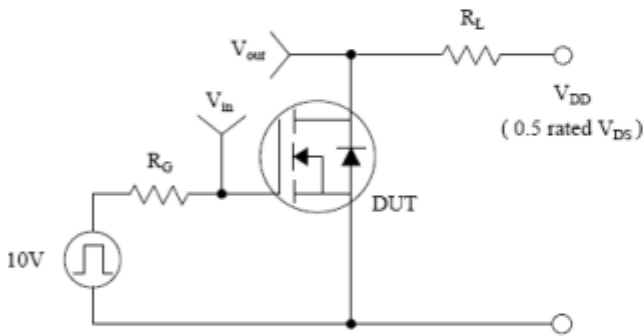
**Figure 11. Transient Thermal Response Curve**

10. Test Circuits and Waveforms

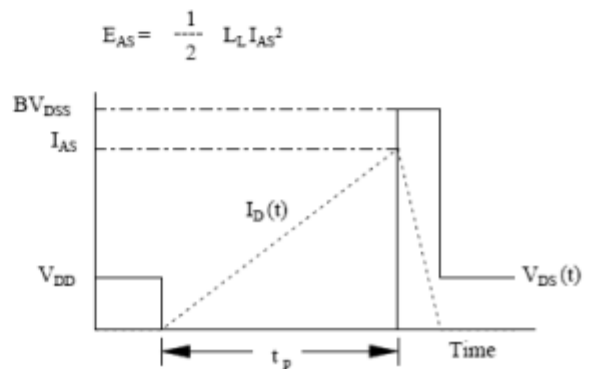
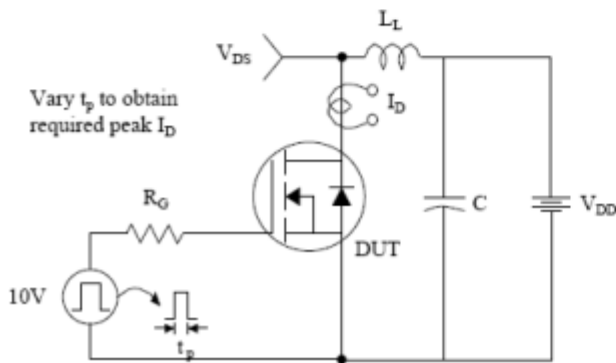
Gate Charge Test Circuit & Waveform



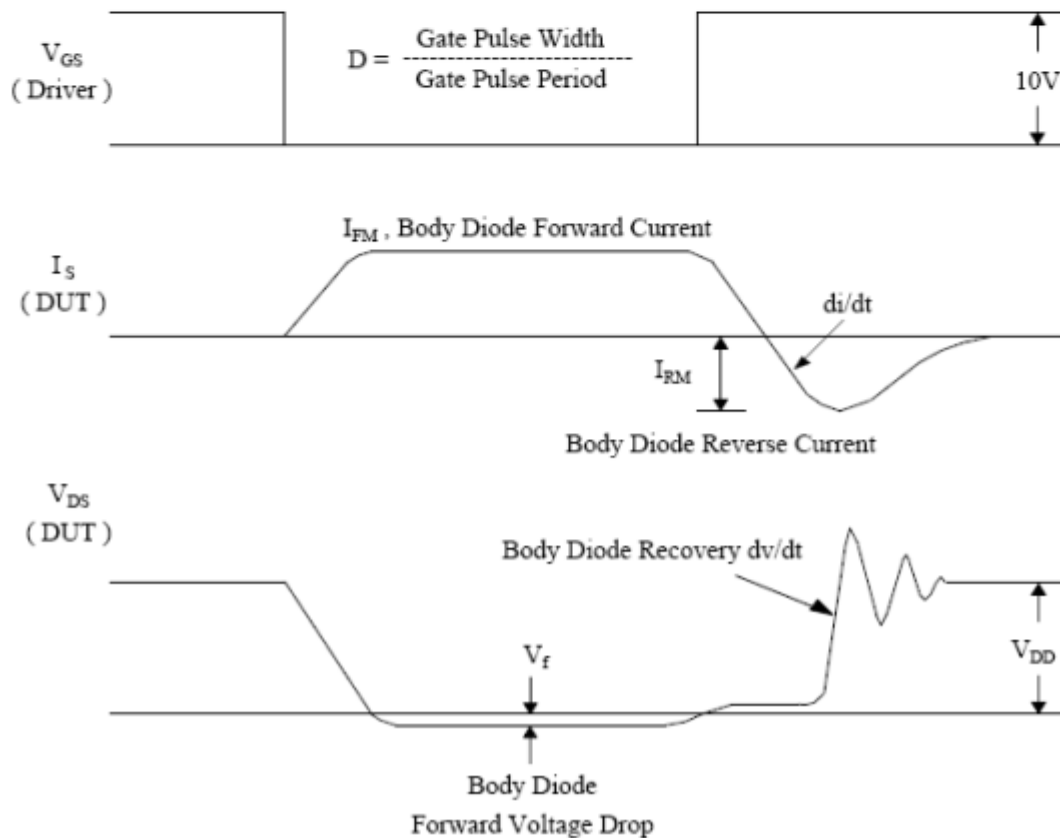
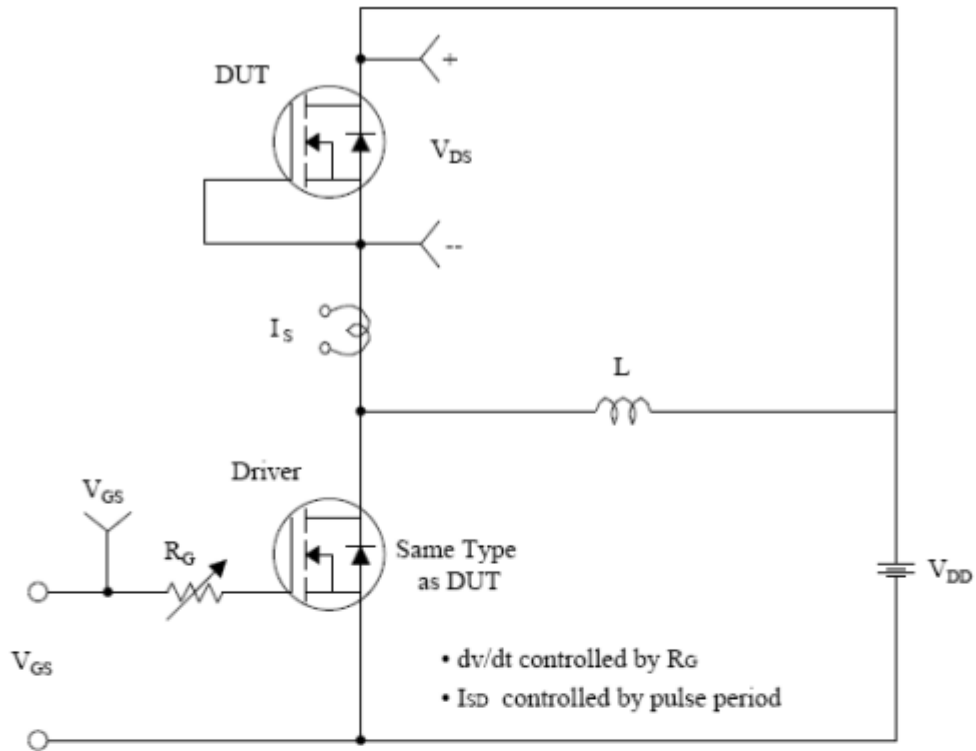
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms



### Peak Diode Recovery dv/dt Test Circuit & Waveforms



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